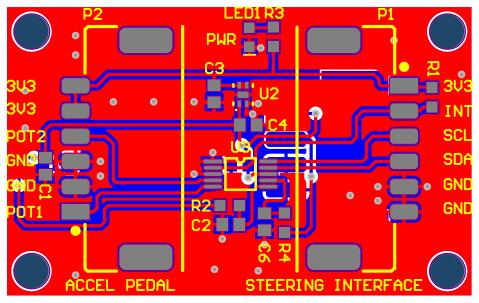
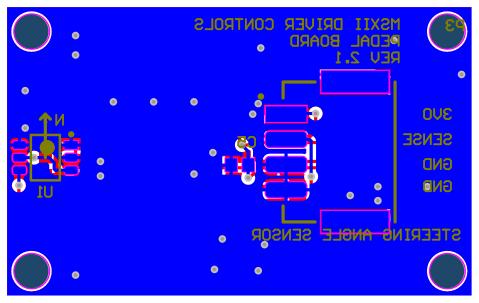


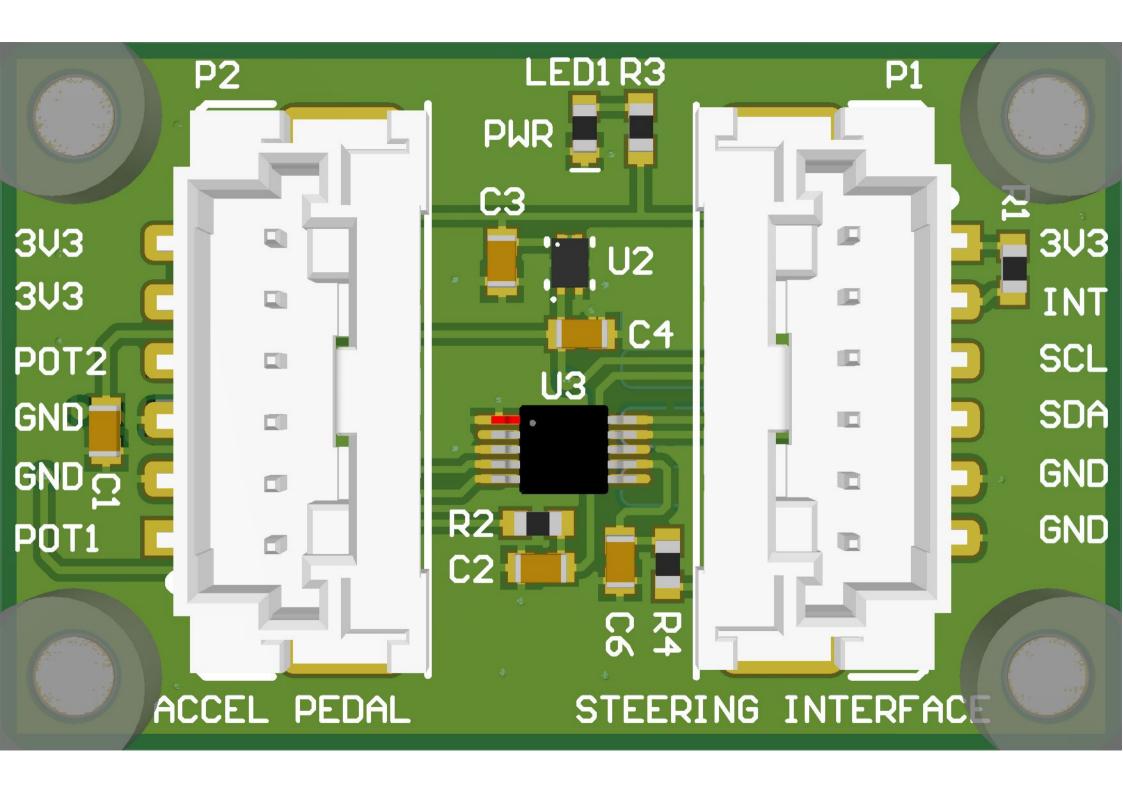
Bill of Materials	
Project:	MSXII_PedalBoard.PrjPcb
Revision:	2.1
Project Lead:	Taiping Li
Generated On:	2018-05-21 7:13:20 PM
Production Quantity:	1
Currency	CAD
Total Parts Count:	17



LibRef	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Supplier Order Qty 1	Supplier Subtotal 1
CAP CER 0.1UF 50V 10% X7R 0603	C1	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.2	1	\$ 0.20
CAP CER 22PF 100V 5% NP0 0603	C2	Murata	GCM1885C2A220JA16D	Digi-Key	490-4942-1-ND	0.15	1	\$ 0.15
CAP CER 1UF 50V 10% X7R 0603	C3	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 1UF 50V 10% X7R 0603	C4	Taiyo Yuden	UMK107AB7105KA-T	Digi-Key	587-3247-1-ND	0.37	1	\$ 0.37
CAP CER 0.1UF 50V 10% X7R 0603	C5	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.2	1	\$ 0.20
CAP CER 0.1UF 50V 10% X7R 0603	C6	Kyocera AVX	06035C-104KAT2A	Digi-Key	478-5052-1-ND	0.2	1	\$ 0.20
LED GREEN CLEAR 2V 0603	LED1	Wurth Electronics	150060VS75000	Digi-Key	732-4980-1-ND	0.18	1	\$ 0.18
CONN 6POS DURA-CLIK 0.079"	P1	Molex	<u>560020-0620</u>	Digi-Key	WM10866CT-ND	1.55	1	\$ 1.55
CONN 6POS DURA-CLIK 0.079"	P2	Molex	560020-0620	Digi-Key	WM10866CT-ND	1.55	1	\$ 1.55
CONN 4POS DURA-CLIK RIGHT ANGLE 0.079"	P3	Molex	502352-0400	Digi-Key	WM7171CT-ND	1.75	1	\$ 1.75
RES 10K OHM 1% 1/10W 0603	R1	<u>Yageo</u>	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13	1	\$ 0.13
RES 100 OHM 1% 1/10W 0603	R2	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND	0.13	1	\$ 0.13
RES 510 OHM 5% 1/10W 0603	R3	Yageo	RC0603JR-07510RL	Digi-Key	311-510GRCT-ND	0.13	1	\$ 0.13
RES 100 OHM 1% 1/10W 0603	R4	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRCT-ND	0.13	1	\$ 0.13
IC SENSOR ROTATIONAL ANGLE 360DEG SOP6	U1	AKM Semiconductor	EM3242	Digi-Key	974-1044-1-ND	6.14	1	\$ 6.14
IC REG LDO 3V 0.2A 4-TDFN	U2	Microchip	MIC94310-PYMT-TR	Digi-Key	576-4761-1-ND	0.37	1	\$ 0.37
IC ADC 12-BIT VSSOP-10	U3	Texas Instruments	ADS1015IDGSR	Digi-Key	296-41185-1-ND	3.54	1	\$ 3.54
							Total:	\$ 17.09







Electrical Rules Check Report

Class	Document	Message
		Successful Compile for MSXII_PedalBoard.PrjPcb
	_	

Design Rules Verification Report

Filename: C:\Users\Taiping\Documents\MidnightSun\hardware\MSXII_PedalBoard\PedalBc

Warnings 0
Rule Violations 36

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.254mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.254mm) (Max=0.254mm) (Preferred=0.254mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)	4
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	10
Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)	22
Silk to Silk (Clearance=0.254mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	36

Hole Size Constraint (Min=0.025mm) (Max=2.54mm) (All)
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(2.5mm,2.5mm) on Multi-Layer Actual Hole Size = 2.7mm
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(2.5mm,21.5mm) on Multi-Layer Actual Hole Size = 2.7mm
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(35.5mm,2.5mm) on Multi-Layer Actual Hole Size = 2.7mm
Hole Size Constraint: (2.7mm > 2.54mm) Pad Free-(35.5mm,21.5mm) on Multi-Layer Actual Hole Size = 2.7mm

Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U1-1(5.65mm,12.5mm) on Bottom Layer And Pad U1-2(5.65mm,11.5mm) on Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U1-2(5.65mm,11.5mm) on Bottom Layer And Pad U1-3(5.65mm,10.5mm) on Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U1-4(1.55mm,10.5mm) on Bottom Layer And Pad U1-5(1.55mm,11.5mm) on Minimum Solder Mask Sliver Constraint: (0.197mm < 0.254mm) Between Pad U1-5(1.55mm,11.5mm) on Bottom Layer And Pad U1-6(1.55mm,12.5mm) on Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U2-1(19mm,15.785mm) on Top Layer And Pad U2-2(19.6mm,15.785mm) on Minimum Solder Mask Sliver Constraint: (0.012mm < 0.254mm) Between Pad U2-1(19mm,15.785mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on Minimum Solder Mask Sliver Constraint: (0.012mm < 0.254mm) Between Pad U2-2(19.6mm,15.785mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on Minimum Solder Mask Sliver Constraint: (0.147mm < 0.254mm) Between Pad U2-3(19.6mm,15.785mm) on Top Layer And Pad U2-4(19mm,17.225mm) on Minimum Solder Mask Sliver Constraint: (0.012mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Pad U2-4(19mm,17.225mm) on Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Pad U2-5(19.3mm,

Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-4(19mm,17.225mm) on Top Layer And Pad U2-5(19.3mm,16.5mm) on

Silk To Solder Mask (Clearance=0.254mm) (IsPad),(All)
Silk To Solder Mask Clearance Constraint: (0.188mm < 0.254mm) Between Arc (18.746mm,15.277mm) on Top Overlay And Pad U2-1(19mm,15.785mm)
Silk To Solder Mask Clearance Constraint: (0.165mm < 0.254mm) Between Pad LED1-2(19.8mm,20.3mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (Collision < 0.254mm) Between Pad P3-(28.188mm,6.4mm) on Bottom Layer And Text "STEERING ANGLE
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad R3-2(21.7mm,21.85mm) on Top Layer And Text "R3" (21.1mm,22.6mm) on
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-1(19mm,15.785mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-2(19.6mm,15.785mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-3(19.6mm,17.225mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U2-4(19mm,17.225mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.193mm < 0.254mm) Between Pad U3-1(16.9mm,11.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.175mm < 0.254mm) Between Pad U3-1(16.9mm,11.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U3-10(21.3mm,11.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-10(21.3mm,11.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-2(16.9mm,10.7mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-3(16.9mm,10.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-4(16.9mm,9.7mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-5(16.9mm,9.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U3-5(16.9mm,9.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.25mm < 0.254mm) Between Pad U3-6(21.3mm,9.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-6(21.3mm,9.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-7(21.3mm,9.7mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-8(21.3mm,10.2mm) on Top Layer And Track
Silk To Solder Mask Clearance Constraint: (0.233mm < 0.254mm) Between Pad U3-9(21.3mm,10.7mm) on Top Layer And Track

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